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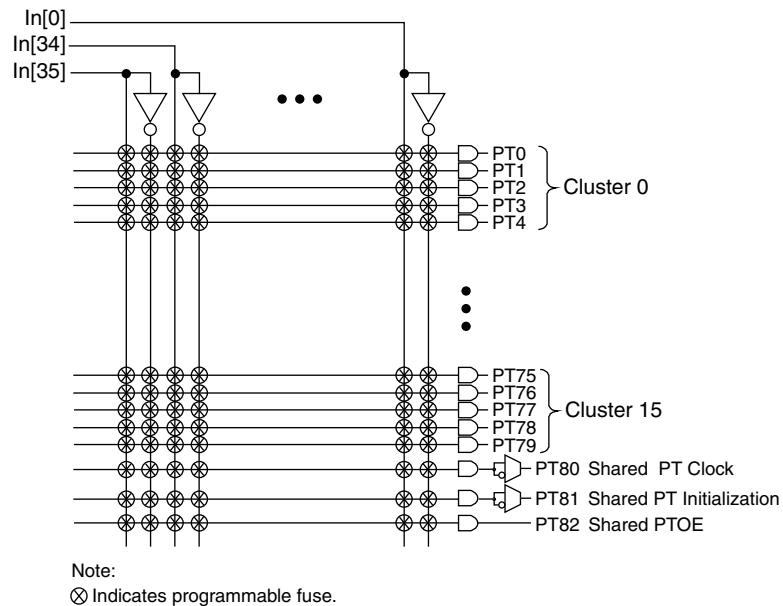
## Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

## Applications of Embedded - CPLDs

### Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	2.3V ~ 2.7V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	64
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256b-75t100c">https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256b-75t100c</a>

**Figure 3. AND Array**

## Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

**Figure 4. Macrocell Slice**

## Product Term Allocator

The product term allocator assigns product terms from a cluster to either logic or control applications as required by the design being implemented. Product terms that are used as logic are steered into a 5-input OR gate associated with the cluster. Product terms that are used for control are steered either to the macrocell or I/O cell associated with the cluster. Table 3 shows the available functions for each of the five product terms in the cluster. The OR gate output connects to the associated I/O cell, providing a fast path for narrow combinatorial functions, and to the logic allocator.

**Table 3. Individual PT Steering**

Product Term	Logic	Control
PT <sub>n</sub>	Logic PT	Single PT for XOR/OR
PT <sub>n+1</sub>	Logic PT	Individual Clock (PT Clock)
PT <sub>n+2</sub>	Logic PT	Individual Initialization or Individual Clock Enable (PT Initialization/CE)
PT <sub>n+3</sub>	Logic PT	Individual Initialization (PT Initialization)
PT <sub>n+4</sub>	Logic PT	Individual OE (PTOE)

## Cluster Allocator

The cluster allocator allows clusters to be steered to neighboring macrocells, thus allowing the creation of functions with more product terms. Table 4 shows which clusters can be steered to which macrocells. Used in this manner, the cluster allocator can be used to form functions of up to 20 product terms. Additionally, the cluster allocator accepts inputs from the wide steering logic. Using these inputs, functions up to 80 product terms can be created.

**Table 4. Available Clusters for Each Macrocell**

Macrocell	Available Clusters			
M0	—	C0	C1	C2
M1	C0	C1	C2	C3
M2	C1	C2	C3	C4
M3	C2	C3	C4	C5
M4	C3	C4	C5	C6
M5	C4	C5	C6	C7
M6	C5	C6	C7	C8
M7	C6	C7	C8	C9
M8	C7	C8	C9	C10
M9	C8	C9	C10	C11
M10	C9	C10	C11	C12
M11	C10	C11	C12	C13
M12	C11	C12	C13	C14
M13	C12	C13	C14	C15
M14	C13	C14	C15	—
M15	C14	C15	—	—

## Wide Steering Logic

The wide steering logic allows the output of the cluster allocator  $n$  to be connected to the input of the cluster allocator  $n+4$ . Thus, cluster chains can be formed with up to 80 product terms, supporting wide product term functions and allowing performance to be increased through a single GLB implementation. Table 5 shows the product term chains.

**Figure 10. Global OE Generation for ispMACH 4032**

## Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E<sup>2</sup> low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

## IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

## I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM® System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

## Supply Current, ispMACH 4000V/B/C

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4032V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	11.8	—	mA
		Vcc = 2.5V	—	11.8	—	mA
		Vcc = 1.8V	—	1.8	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	11.3	—	mA
		Vcc = 2.5V	—	11.3	—	mA
		Vcc = 1.8V	—	1.3	—	mA
<b>ispMACH 4064V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC <sup>5</sup>	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
<b>ispMACH 4128V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	11.5	—	mA
		Vcc = 2.5V	—	11.5	—	mA
		Vcc = 1.8V	—	1.5	—	mA
<b>ispMACH 4256V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	12	—	mA
		Vcc = 2.5V	—	12	—	mA
		Vcc = 1.8V	—	2	—	mA
<b>ispMACH 4384V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	13.5	—	mA
		Vcc = 2.5V	—	13.5	—	mA
		Vcc = 1.8V	—	3.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	Vcc = 3.3V	—	12.5	—	mA
		Vcc = 2.5V	—	12.5	—	mA
		Vcc = 1.8V	—	2.5	—	mA
<b>ispMACH 4512V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	Vcc = 3.3V	—	14	—	mA
		Vcc = 2.5V	—	14	—	mA
		Vcc = 1.8V	—	4	—	mA

**ispMACH 4000Z Internal Timing Parameters**

Over Recommended Operating Conditions

Parameter	Description	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>In/Out Delays</b>								
$t_{IN}$	Input Buffer Delay	—	0.75	—	0.80	—	0.75	ns
$t_{GOE}$	Global OE Pin Delay	—	2.25	—	2.25	—	2.30	ns
$t_{GCLK\_IN}$	Global Clock Input Buffer Delay	—	1.60	—	1.60	—	1.95	ns
$t_{BUF}$	Delay through Output Buffer	—	0.75	—	0.90	—	0.90	ns
$t_{EN}$	Output Enable Time	—	2.25	—	2.25	—	2.50	ns
$t_{DIS}$	Output Disable Time	—	1.35	—	1.35	—	2.50	ns
<b>Routing/GLB Delays</b>								
$t_{ROUTE}$	Delay through GRP	—	1.60	—	1.60	—	2.15	ns
$t_{MCELL}$	Macrocell Delay	—	0.65	—	0.75	—	0.85	ns
$t_{INREG}$	Input Buffer to Macrocell Register Delay	—	0.91	—	1.00	—	1.00	ns
$t_{FBK}$	Internal Feedback Delay	—	0.05	—	0.00	—	0.00	ns
$t_{PDb}$	5-PT Bypass Propagation Delay	—	0.40	—	0.40	—	0.40	ns
$t_{PDi}$	Macrocell Propagation Delay	—	0.25	—	0.25	—	0.65	ns
<b>Register/Latch Delays</b>								
$t_S$	D-Register Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
$t_{S\_PT}$	D-Register Setup Time (Product Term Clock)	1.35	—	1.95	—	1.90	—	ns
$t_{ST}$	T-Register Setup Time (Global Clock)	1.00	—	1.15	—	1.10	—	ns
$t_{ST\_PT}$	T-Register Setup Time (Product Term Clock)	1.55	—	1.75	—	2.10	—	ns
$t_H$	D-Register Hold Time	1.40	—	1.55	—	1.80	—	ns
$t_{HT}$	T-Register Hold Time	1.40	—	1.55	—	1.80	—	ns
$t_{SIR}$	D-Input Register Setup Time (Global Clock)	0.94	—	0.90	—	1.50	—	ns
$t_{SIR\_PT}$	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
$t_{HIR}$	D-Input Register Hold Time (Global Clock)	1.06	—	1.20	—	1.10	—	ns
$t_{HIR\_PT}$	D-Input Register Hold Time (Product Term Clock)	0.88	—	1.00	—	1.00	—	ns
$t_{COi}$	Register Clock to Output/Feedback MUX Time	—	0.65	—	0.70	—	0.65	ns
$t_{CES}$	Clock Enable Setup Time	1.00	—	2.00	—	2.00	—	ns
$t_{CEH}$	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
$t_{SL}$	Latch Setup Time (Global Clock)	0.80	—	0.95	—	0.90	—	ns
$t_{SL\_PT}$	Latch Setup Time (Product Term Clock)	1.55	—	1.95	—	1.90	—	ns
$t_{HL}$	Latch Hold Time	1.40	—	1.80	—	1.80	—	ns
$t_{GOi}$	Latch Gate to Output/Feedback MUX Time	—	0.40	—	0.33	—	0.33	ns
$t_{PDLi}$	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.30	—	0.25	—	0.25	ns
$t_{SRi}$	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.28	—	0.28	—	1.27	ns
$t_{SRR}$	Asynchronous Reset or Set Recovery Delay	—	2.00	—	1.67	—	1.80	ns
<b>Control Delays</b>								
$t_{BCLK}$	GLB PT Clock Delay	—	1.30	—	1.50	—	1.55	ns
$t_{PTCLK}$	Macrocell PT Clock Delay	—	1.50	—	1.70	—	1.55	ns
$t_{BSR}$	GLB PT Set/Reset Delay	—	1.10	—	1.83	—	1.83	ns
$t_{PTSR}$	Macrocell PT Set/Reset Delay	—	1.22	—	2.02	—	1.83	ns

**ispMACH 4000V/B/C Timing Adders<sup>1</sup>**

Adder Type	Base Parameter	Description	-25		-27		-3		-35		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Optional Delay Adders</b>											
$t_{INDIO}$	$t_{INREG}$	Input register delay	—	0.95	—	1.00	—	1.00	—	1.00	ns
$t_{EXP}$	$t_{MCELL}$	Product term expander delay	—	0.33	—	0.33	—	0.33	—	0.33	ns
$t_{ORP}$	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	—	0.05	ns
$t_{BLA}$	$t_{ROUTE}$	Additional block loading adder	—	0.03	—	0.05	—	0.05	—	0.05	ns
<b><math>t_{IOI}</math> Input Adjusters</b>											
LVTTL_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVTTL standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using PCI compatible input	—	0.60	—	0.60	—	0.60	—	0.60	ns
<b><math>t_{IOO}</math> Output Adjusters</b>											
LVTTL_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
Slow Slew	$t_{BUF}$ , $t_{EN}$	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

**ispMACH 4000V/B/C Timing Adders<sup>1</sup> (Cont.)**

Adder Type	Base Parameter	Description	-5		-75		-10		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
<b>Optional Delay Adders</b>									
$t_{INDIO}$	$t_{INREG}$	Input register delay	—	1.00	—	1.00	—	1.00	ns
$t_{EXP}$	$t_{MCELL}$	Product term expander delay	—	0.33	—	0.33	—	0.33	ns
$t_{ORP}$	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	ns
$t_{BLA}$	$t_{ROUTE}$	Additional block loading adder	—	0.05	—	0.05	—	0.05	ns
<b><math>t_{IOI}</math> Input Adjusters</b>									
LVTTL_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVTTL standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	$t_{IN}$ , $t_{GCLK\_IN}$ , $t_{GOE}$	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
<b><math>t_{IOO}</math> Output Adjusters</b>									
LVTTL_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	$t_{BUF}$ , $t_{EN}$ , $t_{DIS}$	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	$t_{BUF}$ , $t_{EN}$	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

**ispMACH 4000Z Timing Adders<sup>1</sup>**

Adder Type	Base Parameter	Description	-35		-37		-42		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
<b>Optional Delay Adders</b>									
t <sub>INDIO</sub>	t <sub>INREG</sub>	Input register delay	—	1.00	—	1.00	—	1.30	ns
t <sub>EXP</sub>	t <sub>MCELL</sub>	Product term expander delay	—	0.40	—	0.40	—	0.45	ns
t <sub>ORP</sub>	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t <sub>BLA</sub>	t <sub>ROUTE</sub>	Additional block loading adder	—	0.04	—	0.05	—	0.05	ns
<b>t<sub>IOI</sub> Input Adjusters</b>									
LVTTL_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVTTL standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS33_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVCMOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS25_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVCMOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVCMOS18_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVCMOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
<b>t<sub>IOO</sub> Output Adjusters</b>									
LVTTL_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS33_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVCMOS25_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVCMOS18_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t <sub>BUF</sub> , t <sub>EN</sub>	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding the use of these adders.

## Signal Descriptions

Signal Names		Description
TMS		Input – This pin is the IEEE 1149.1 Test Mode Select input, which is used to control the state machine.
TCK		Input – This pin is the IEEE 1149.1 Test Clock input pin, used to clock through the state machine.
TDI		Input – This pin is the IEEE 1149.1 Test Data In pin, used to load data.
TDO		Output – This pin is the IEEE 1149.1 Test Data Out pin used to shift data out.
GOE0/IO, GOE1/IO		These pins are configured to be either Global Output Enable Input or as general I/O pins.
GND		Ground
NC		Not Connected
V <sub>CC</sub>		The power supply pins for logic core and JTAG port.
CLK0/I, CLK1/I, CLK2/I, CLK3/I		These pins are configured to be either CLK input or as an input.
V <sub>CC00</sub> , V <sub>CC01</sub>		The power supply pins for each I/O bank.
yzz		Input/Output <sup>1</sup> – These are the general purpose I/O used by the logic array. y is GLB reference (alpha) and z is macrocell reference (numeric). z: 0-15.
		ispMACH 4032
		ispMACH 4064
		ispMACH 4128
		ispMACH 4256
		ispMACH 4384
		ispMACH 4512
		y: A-B
		y: A-D
		y: A-H
		y: A-P
		y: A-P, AX-HX
		y: A-P, AX-PX

1. In some packages, certain I/Os are only available for use as inputs. See the signal connections table for details.

## ispMACH 4000V/B/C ORP Reference Table

	4032V/B/C		4064V/B/C			4128V/B/C			4256V/B/C				4384V/B/C		4512V/B/C	
Number of I/Os	30 <sup>1</sup>	32	30 <sup>2</sup>	32	64	64	92 <sup>3</sup>	96	64	96 <sup>4</sup>	128	160	128	192	128	208
Number of GLBs	2	2	4	4	4	8	8	8	16	16	16	16	16	16	16	16
Number of I/Os / GLB	16	16	8	8	16	8	12	12	4	8	8	10	8	8	8	Mixture of 8 & 4 <sup>5</sup>
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB		8 I/Os / GLB		12 I/Os / GLB		4 I/Os / GLB		8 I/Os / GLB		10 I/Os / GLB	
															8 I/Os / GLB	
															4 I/Os / GLB	

1. 32-macrocell device, 44 TQFP: 2 GLBs have 15 out of 16 I/Os bonded out.

2. 64-macrocells device, 44 TQFP: 2 GLBs have 7 out of 8 I/Os bonded out.

3. 128-macrocell device, 128 TQFP: 4 GLBs have 11 out of 12 I/Os

4. 256-macrocell device, 144 TQFP: 16 GLBs have 6 I/Os per

5. 512-macrocell device: 20 GLBs have 8 I/Os per, 12 GLBs have 4 I/Os per

## ispMACH 4000Z ORP Reference Table

	4032Z		4064Z			4128Z			4256Z			
Number of I/Os	32	32	64			64	96	64	96 <sup>1</sup>	128		
Number of GLBs	2	4	4			8	8	16	16	16		
Number of I/Os / GLB	16	8	16			8	12	4	8	8		
Reference ORP Table	16 I/Os / GLB		8 I/Os / GLB		16 I/Os / GLB		8 I/Os / GLB		12 I/Os / GLB		4 I/Os / GLB	

1. 256-macrocell device, 132 csBGA: 16 GLBs have 6 I/Os per

**ispMACH 4000V/B/C/Z Power Supply and NC Connections<sup>1</sup>**

Signal	44-pin TQFP <sup>2</sup>	48-pin TQFP <sup>2</sup>	56-ball csBGA <sup>3</sup>	100-pin TQFP <sup>2</sup>	128-pin TQFP <sup>2</sup>
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	<b>4032Z:</b> A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.

2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.

3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4032V/B/C and 4064V/B/C Logic Signal Connections:  
44-Pin TQFP**

Pin Number	Bank Number	ispMACH 4032V/B/C		ispMACH 4064V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	TDI	-	TDI	-
2	0	A5	A^5	A10	A^5
3	0	A6	A^6	A12	A^6
4	0	A7	A^7	A14	A^7
5	0	GND (Bank 0)	-	GND (Bank 0)	-
6	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
7	0	A8	A^8	B0	B^0
8	0	A9	A^9	B2	B^1
9	0	A10	A^10	B4	B^2
10	-	TCK	-	TCK	-
11	-	VCC	-	VCC	-
12	-	GND	-	GND	-
13	0	A12	A^12	B8	B^4
14	0	A13	A^13	B10	B^5
15	0	A14	A^14	B12	B^6
16	0	A15	A^15	B14	B^7
17	1	CLK2/I	-	CLK2/I	-
18	1	B0	B^0	C0	C^0
19	1	B1	B^1	C2	C^1
20	1	B2	B^2	C4	C^2
21	1	B3	B^3	C6	C^3
22	1	B4	B^4	C8	C^4
23	-	TMS	-	TMS	-
24	1	B5	B^5	C10	C^5
25	1	B6	B^6	C12	C^6
26	1	B7	B^7	C14	C^7
27	1	GND (Bank 1)	-	GND (Bank 1)	-
28	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-
29	1	B8	B^8	D0	D^0
30	1	B9	B^9	D2	D^1
31	1	B10	B^10	D4	D^2
32	-	TDO	-	TDO	-
33	-	VCC	-	VCC	-
34	-	GND	-	GND	-
35	1	B12	B^12	D8	D^4
36	1	B13	B^13	D10	D^5
37	1	B14	B^14	D12	D^6
38	1	B15/GOE1	B^15	D14/GOE1	D^7
39	0	CLK0/I	-	CLK0/I	-
40	0	A0/GOE0	A^0	A0/GOE0	A^0
41	0	A1	A^1	A2	A^1

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:  
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E3	0	NC	-	B8	B^6	D12	D^6
F2	0	A12	A^12	B9	B^7	D10	D^5
F1	0	A13	A^13	B10	B^8	D8	D^4
F3	0	A14	A^14	B12	B^9	D6	D^3
G1	0	A15	A^15	B13	B^10	D4	D^2
G2	0	I	-	B14	B^11	D2	D^1
G3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
H2	0	NC	-	C14	C^11	E2	E^1
H1	0	B15	B^15	C13	C^10	E4	E^2
H3	0	B14	B^14	C12	C^9	E6	E^3
J1	0	B13	B^13	C10	C^8	E8	E^4
J2	0	B12	B^12	C9	C^7	E10	E^5
J3	0	NC	-	C8	C^6	E12	E^6
K2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
K1	0	NC	-	C6	C^5	F2	F^1
K3	0	B11	B^11	C5	C^4	F4	F^2
L2	0	B10	B^10	C4	C^3	F6	F^3
L1	0	B9	B^9	C2	C^2	F8	F^4
L3	0	B8	B^8	C1	C^1	F10	F^5
M1	0	I	-	C0	C^0	F12	F^6
M2	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N1	-	TCK	-	TCK	-	TCK	-
P1	-	VCC	-	VCC	-	VCC	-
P2	-	GND	-	GND	-	GND	-
N2	0	I	-	D14	D^11	G12	G^6
P3	0	B7	B^7	D13	D^10	G10	G^5
M3	0	B6	B^6	D12	D^9	G8	G^4
N3	0	B5	B^5	D10	D^8	G6	G^3
P4	0	B4	B^4	D9	D^7	G4	G^2
M4	0	NC	-	D8	D^6	G2	G^1
N4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
P5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N5	0	NC	-	D6	D^5	H12	H^6
M5	0	B3	B^3	D5	D^4	H10	H^5
N6	0	B2	B^2	D4	D^3	H8	H^4
P6	0	B1	B^1	D2	D^2	H6	H^3
M6	0	B0	B^0	D1	D^1	H4	H^2
P7	0	NC	-	D0	D^0	H2	H^1
N7	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
M7	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
N8	-	VCC	-	VCC	-	VCC	-

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:  
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
C12	1	O0	O^0	O2	O^2	GX0	GX^0	OX0	OX^0
E10	1	NC	-	O1	O^1	CX8	CX^4	MX0	MX^0
A13	1	NC	-	O0	O^0	CX10	CX^5	MX4	MX^1
D12	1	NC	-	NC	-	NC	-	LX0	LX^0
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B12	1	NC	-	NC	-	NC	-	LX4	LX^1
A12	1	NC	-	NC	-	EX2	EX^1	LX8	LX^2
B11	1	NC	-	NC	-	EX0	EX^0	LX12	LX^3
A11	1	NC	-	P14	P^9	CX12	CX^6	MX8	MX^2
D10	1	NC	-	P12	P^8	CX14	CX^7	MX12	MX^3
C10	1	P14	P^7	P10	P^7	HX14	HX^7	PX14	PX^7
B10	1	P12	P^6	P9	P6	HX12	HX^6	PX12	PX^6
A10	1	P10	P^5	P8	P^5	HX10	HX^5	PX10	PX^5
A9	1	P8	P^4	P6	P^4	HX8	HX^4	PX8	PX^4
F9	1	P6	P^3	P4	P^3	HX6	HX^3	PX6	PX^3
B9	1	P4	P^2	P2	P^2	HX4	HX^2	PX4	PX^2
E9	1	P2/GOE1	P^1	P1/GOE1	P^1	HX2/GOE1	HX^1	PX2/GOE1	PX^1
C9	1	P0	P^0	P0	P^0	HX0	HX^0	PX0	PX^0
-	-	GND	-	GND	-	GND	-	GND	-
D9	1	CLK3/I	-	CLK3/I	-	CLK3/I	-	CLK3/I	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
B8	0	CLK0/I	-	CLK0/I	-	CLK0/I	-	CLK0/I	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
D8	0	A0	A^0	A0	A^0	A0	A^0	A0	A^0
C8	0	A2/GOE0	A^1	A1/GOE0	A^1	A2/GOE0	A^1	A2/GOE0	A^1
A8	0	A4	A^2	A2	A^2	A4	A^2	A4	A^2
A7	0	A6	A^3	A4	A^3	A6	A^3	A6	A^3
B7	0	A8	A^4	A6	A^4	A8	A^4	A8	A^4
E8	0	A10	A^5	A8	A^5	A10	A^5	A10	A^5
D7	0	A12	A^6	A9	A^6	A12	A^6	A12	A^6
F8	0	A14	A^7	A10	A^7	A14	A^7	A14	A^7
C7	0	NC	-	A12	A^8	F14	F^7	D0	D^0
A6	0	NC	-	A14	A^9	F12	F^6	D4	D^1
B6	0	NC	-	NC	-	D14	D^7	E0	E^0
A5	0	NC	-	NC	-	D12	D^6	E4	E^1
B5	0	NC	-	NC	-	NC	-	E8	E^2
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
D5	0	NC	-	NC	-	NC	-	E12	E^3
A4	0	NC	-	B0	B^0	F10	F^5	D8	D^2

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:  
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E7	0	NC	-	B1	B^1	F8	F^4	D12	D^3
A3	0	B0	B^0	B2	B^2	B0	B^0	B0	B^0
F7	0	B2	B^1	B4	B^3	B2	B^1	B2	B^1
B4	0	B4	B^2	B6	B^4	B4	B^2	B4	B^2
C5	0	B6	B^3	B8	B^5	B6	B^3	B6	B^3
A2	0	B8	B^4	B9	B^6	B8	B^4	B8	B^4
E6	0	B10	B^5	B10	B^7	B10	B^5	B10	B^5
B3	0	B12	B^6	B12	B^8	B12	B^6	B12	B^6
C4	0	B14	B^7	B14	B^9	B14	B^7	B14	B^7
D4	0	NC	-	NC	-	D10	D^5	F0	F^0
E5	0	NC	-	NC	-	D8	D^4	F2	F^1
-	-	VCC	-	VCC	-	VCC	-	VCC	-
-	-	-	-	-	-	GND	-	GND	-
-	0	-	-	-	-	GND (Bank 0)	-	GND (Bank 0)	-

Note: VCC, VCCO and GND are tied together to their respective common signal on the package substrate. See Power Supply and NC Connections table for VCC/ VCCO/GND pin definitions.

## Ordering Information

Note: ispMACH 4000 devices are all dual marked except the slowest commercial speed grade ispMACH 4000Z devices. For example, the commercial speed grade LC4128C-5T100C is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade ispMACH 4000Z devices are marked as commercial grade only.

### Conventional Packaging

#### ispMACH 4000ZC (Zero Power, 1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35M56C	32	1.8	3.5	csBGA	56	32	C
	LC4032ZC-5M56C	32	1.8	5	csBGA	56	32	C
	LC4032ZC-75M56C	32	1.8	7.5	csBGA	56	32	C
	LC4032ZC-35T48C	32	1.8	3.5	TQFP	48	32	C
	LC4032ZC-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032ZC-75T48C	32	1.8	7.5	TQFP	48	32	C
LC4064ZC	LC4064ZC-37M132C	64	1.8	3.7	csBGA	132	64	C
	LC4064ZC-5M132C	64	1.8	5	csBGA	132	64	C
	LC4064ZC-75M132C	64	1.8	7.5	csBGA	132	64	C
	LC4064ZC-37T100C	64	1.8	3.7	TQFP	100	64	C
	LC4064ZC-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064ZC-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064ZC-37M56C	64	1.8	3.7	csBGA	56	32	C
	LC4064ZC-5M56C	64	1.8	5	csBGA	56	32	C
	LC4064ZC-75M56C	64	1.8	7.5	csBGA	56	32	C
	LC4064ZC-37T48C	64	1.8	3.7	TQFP	48	32	C
	LC4064ZC-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064ZC-75T48C	64	1.8	7.5	TQFP	48	32	C
LC4128ZC	LC4128ZC-42M132C	128	1.8	4.2	csBGA	132	96	C
	LC4128ZC-75M132C	128	1.8	7.5	csBGA	132	96	C
	LC4128ZC-42T100C	128	1.8	4.2	TQFP	100	64	C
	LC4128ZC-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256ZC	LC4256ZC-45T176C	256	1.8	4.5	TQFP	176	128	C
	LC4256ZC-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256ZC-45M132C	256	1.8	4.5	csBGA	132	96	C
	LC4256ZC-75M132C	256	1.8	7.5	csBGA	132	96	C
	LC4256ZC-45T100C	256	1.8	4.5	TQFP	100	64	C
	LC4256ZC-75T100C	256	1.8	7.5	TQFP	100	64	C

#### ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5M56I	32	1.8	5	csBGA	56	32	I
	LC4032ZC-75M56I	32	1.8	7.5	csBGA	56	32	I
	LC4032ZC-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032ZC-75T48I	32	1.8	7.5	TQFP	48	32	I

## ispMACH 4000B (2.5V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4256B	LC4256B-3FT256AC	256	2.5	3	ftBGA	256	128	C
	LC4256B-5FT256AC	256	2.5	5	ftBGA	256	128	C
	LC4256B-75FT256AC	256	2.5	7.5	ftBGA	256	128	C
	LC4256B-3FT256BC	256	2.5	3	ftBGA	256	160	C
	LC4256B-5FT256BC	256	2.5	5	ftBGA	256	160	C
	LC4256B-75FT256BC	256	2.5	7.5	ftBGA	256	160	C
	LC4256B-3F256AC <sup>1</sup>	256	2.5	3	fpBGA	256	128	C
	LC4256B-5F256AC <sup>1</sup>	256	2.5	5	fpBGA	256	128	C
	LC4256B-75F256AC <sup>1</sup>	256	2.5	7.5	fpBGA	256	128	C
	LC4256B-3F256BC <sup>1</sup>	256	2.5	3	fpBGA	256	160	C
	LC4256B-5F256BC <sup>1</sup>	256	2.5	5	fpBGA	256	160	C
	LC4256B-75F256BC <sup>1</sup>	256	2.5	7.5	fpBGA	256	160	C
	LC4256B-3T176C	256	2.5	3	TQFP	176	128	C
	LC4256B-5T176C	256	2.5	5	TQFP	176	128	C
	LC4256B-75T176C	256	2.5	7.5	TQFP	176	128	C
LC4384B	LC4384B-35FT256C	384	2.5	3.5	ftBGA	256	192	C
	LC4384B-5FT256C	384	2.5	5	ftBGA	256	192	C
	LC4384B-75FT256C	384	2.5	7.5	ftBGA	256	192	C
	LC4384B-35F256C <sup>1</sup>	384	2.5	3.5	fpBGA	256	192	C
	LC4384B-5F256C <sup>1</sup>	384	2.5	5	fpBGA	256	192	C
	LC4384B-75F256C <sup>1</sup>	384	2.5	7.5	fpBGA	256	192	C
	LC4384B-35T176C	384	2.5	3.5	TQFP	176	128	C
	LC4384B-5T176C	384	2.5	5	TQFP	176	128	C
LC4512B	LC4512B-35FT256C	512	2.5	3.5	ftBGA	256	208	C
	LC4512B-5FT256C	512	2.5	5	ftBGA	256	208	C
	LC4512B-75FT256C	512	2.5	7.5	ftBGA	256	208	C
	LC4512B-35F256C <sup>1</sup>	512	2.5	3.5	fpBGA	256	208	C
	LC4512B-5F256C <sup>1</sup>	512	2.5	5	fpBGA	256	208	C
	LC4512B-75F256C <sup>1</sup>	512	2.5	7.5	fpBGA	256	208	C
	LC4512B-35T176C	512	2.5	3.5	TQFP	176	128	C
	LC4512B-5T176C	512	2.5	5	TQFP	176	128	C
	LC4512B-75T176C	512	2.5	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000V (3.3V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FT256AI	256	3.3	5	ftBGA	256	128	I
	LC4256V-75FT256AI	256	3.3	7.5	ftBGA	256	128	I
	LC4256V-10FT256AI	256	3.3	10	ftBGA	256	128	I
	LC4256V-5FT256BI	256	3.3	5	ftBGA	256	160	I
	LC4256V-75FT256BI	256	3.3	7.5	ftBGA	256	160	I
	LC4256V-10FT256BI	256	3.3	10	ftBGA	256	160	I
	LC4256V-5F256AI <sup>1</sup>	256	3.3	5	fpBGA	256	128	I
	LC4256V-75F256AI <sup>1</sup>	256	3.3	7.5	fpBGA	256	128	I
	LC4256V-10F256AI <sup>1</sup>	256	3.3	10	fpBGA	256	128	I
	LC4256V-5F256BI <sup>1</sup>	256	3.3	5	fpBGA	256	160	I
	LC4256V-75F256BI <sup>1</sup>	256	3.3	7.5	fpBGA	256	160	I
	LC4256V-10F256BI <sup>1</sup>	256	3.3	10	fpBGA	256	160	I
	LC4256V-5T176I	256	3.3	5	TQFP	176	128	I
	LC4256V-75T176I	256	3.3	7.5	TQFP	176	128	I
	LC4256V-10T176I	256	3.3	10	TQFP	176	128	I
	LC4256V-5T144I	256	3.3	5	TQFP	144	96	I
	LC4256V-75T144I	256	3.3	7.5	TQFP	144	96	I
	LC4256V-10T144I	256	3.3	10	TQFP	144	96	I
	LC4256V-5T100I	256	3.3	5	TQFP	100	64	I
	LC4256V-75T100I	256	3.3	7.5	TQFP	100	64	I
	LC4256V-10T100I	256	3.3	10	TQFP	100	64	I
LC4384V	LC4384V-5FT256I	384	3.3	5	ftBGA	256	192	I
	LC4384V-75FT256I	384	3.3	7.5	ftBGA	256	192	I
	LC4384V-10FT256I	384	3.3	10	ftBGA	256	192	I
	LC4384V-5F256I <sup>1</sup>	384	3.3	5	fpBGA	256	192	I
	LC4384V-75F256I <sup>1</sup>	384	3.3	7.5	fpBGA	256	192	I
	LC4384V-10F256I <sup>1</sup>	384	3.3	10	fpBGA	256	192	I
	LC4384V-5T176I	384	3.3	5	TQFP	176	128	I
	LC4384V-75T176I	384	3.3	7.5	TQFP	176	128	I
	LC4384V-10T176I	384	3.3	10	TQFP	176	128	I
LC4512V	LC4512V-5FT256I	512	3.3	5	ftBGA	256	208	I
	LC4512V-75FT256I	512	3.3	7.5	ftBGA	256	208	I
	LC4512V-10FT256I	512	3.3	10	ftBGA	256	208	I
	LC4512V-5F256I <sup>1</sup>	512	3.3	5	fpBGA	256	208	I
	LC4512V-75F256I <sup>1</sup>	512	3.3	7.5	fpBGA	256	208	I
	LC4512V-10F256I <sup>1</sup>	512	3.3	10	fpBGA	256	208	I
	LC4512V-5T176I	512	3.3	5	TQFP	176	128	I
	LC4512V-75T176I	512	3.3	7.5	TQFP	176	128	I
	LC4512V-10T176I	512	3.3	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4064ZC	LC4064ZC-5MN132I	64	1.8	5	Lead-free csBGA	132	64	I
	LC4064ZC-75MN132I	64	1.8	7.5	Lead-free csBGA	132	64	I
	LC4064ZC-5TN100I	64	1.8	5	Lead-free TQFP	100	64	I
	LC4064ZC-75TN100I	64	1.8	7.5	Lead-free TQFP	100	64	I
	LC4064ZC-5MN56I	64	1.8	5	Lead-free csBGA	56	32	I
	LC4064ZC-75MN56I	64	1.8	7.5	Lead-free csBGA	56	32	I
	LC4064ZC-5TN48I	64	1.8	5	Lead-free TQFP	48	32	I
	LC4064ZC-75TN48I	64	1.8	7.5	Lead-free TQFP	48	32	I
LC4128ZC	LC4128ZC-75MN132I	128	1.8	7.5	Lead-free csBGA	132	96	I
	LC4128ZC-75TN100I	128	1.8	7.5	Lead-free TQFP	100	64	I
LC4256ZC	LC4256ZC-75TN176I	256	1.8	7.5	Lead-free TQFP	176	128	I
	LC4256ZC-75MN132I	256	1.8	7.5	Lead-free csBGA	132	96	I
	LC4256ZC-75TN100I	256	1.8	7.5	Lead-free TQFP	100	64	I

## ispMACH 4000Z (Zero Power, 1.8V) Lead-Free Extended Temperature Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-75TN48E	32	1.8	7.5	Lead-free TQFP	48	32	E
LC4064ZC	LC4064ZC-75TN100E	64	1.8	7.5	Lead-free TQFP	100	64	E
	LC4064ZC-75TN48E	64	1.8	7.5	Lead-free TQFP	48	32	E
LC4128ZC	LC4128ZC-75TN100E	128	1.8	7.5	Lead-free TQFP	100	64	E
LC4256ZC	LC4256ZC-75TN176E	256	1.8	7.5	Lead-free TQFP	176	128	E
	LC4256ZC-75TN100E	256	1.8	7.5	Lead-free TQFP	100	64	E

## ispMACH 4000C (1.8V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-25TN48C	32	1.8	2.5	Lead-free TQFP	48	32	C
	LC4032C-5TN48C	32	1.8	5	Lead-free TQFP	48	32	C
	LC4032C-75TN48C	32	1.8	7.5	Lead-free TQFP	48	32	C
	LC4032C-25TN44C	32	1.8	2.5	Lead-free TQFP	44	30	C
	LC4032C-5TN44C	32	1.8	5	Lead-free TQFP	44	30	C
	LC4032C-75TN44C	32	1.8	7.5	Lead-free TQFP	44	30	C

## ispMACH 4000B (2.5V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-25TN48C	32	2.5	2.5	Lead-Free TQFP	48	32	C
	LC4032B-5TN48C	32	2.5	5	Lead-Free TQFP	48	32	C
	LC4032B-75TN48C	32	2.5	7.5	Lead-Free TQFP	48	32	C
	LC4032B-25TN44C	32	2.5	2.5	Lead-Free TQFP	44	30	C
	LC4032B-5TN44C	32	2.5	5	Lead-Free TQFP	44	30	C
	LC4032B-75TN44C	32	2.5	7.5	Lead-Free TQFP	44	30	C
LC4064B	LC4064B-25TN100C	64	2.5	2.5	Lead-Free TQFP	100	64	C
	LC4064B-5TN100C	64	2.5	5	Lead-Free TQFP	100	64	C
	LC4064B-75TN100C	64	2.5	7.5	Lead-Free TQFP	100	64	C
	LC4064B-25TN48C	64	2.5	2.5	Lead-Free TQFP	48	32	C
	LC4064B-5TN48C	64	2.5	5	Lead-Free TQFP	48	32	C
	LC4064B-75TN48C	64	2.5	7.5	Lead-Free TQFP	48	32	C
	LC4064B-25TN44C	64	2.5	2.5	Lead-Free TQFP	44	30	C
	LC4064B-5TN44C	64	2.5	5	Lead-Free TQFP	44	30	C
	LC4064B-75TN44C	64	2.5	7.5	Lead-Free TQFP	44	30	C
LC4128B	LC4128B-27TN128C	128	2.5	2.7	Lead-Free TQFP	128	92	C
	LC4128B-5TN128C	128	2.5	5	Lead-Free TQFP	128	92	C
	LC4128B-75TN128C	128	2.5	7.5	Lead-Free TQFP	128	92	C
	LC4128B-27TN100C	128	2.5	2.7	Lead-Free TQFP	100	92	C
	LC4128B-5TN100C	128	2.5	5	Lead-Free TQFP	100	92	C
	LC4128B-75TN100C	128	2.5	7.5	Lead-Free TQFP	100	92	C
LC4256B	LC4256B-3FTN256AC	256	2.5	3	Lead-Free ftBGA	256	128	C
	LC4256B-5FTN256AC	256	2.5	5	Lead-Free ftBGA	256	128	C
	LC4256B-75FTN256AC	256	2.5	7.5	Lead-Free ftBGA	256	128	C
	LC4256B-3FTN256BC	256	2.5	3	Lead-Free ftBGA	256	160	C
	LC4256B-5FTN256BC	256	2.5	5	Lead-Free ftBGA	256	160	C
	LC4256B-75FTN256BC	256	2.5	7.5	Lead-Free ftBGA	256	160	C
	LC4256B-3FN256AC <sup>1</sup>	256	2.5	3	Lead-Free fpBGA	256	128	C
	LC4256B-5FN256AC <sup>1</sup>	256	2.5	5	Lead-Free fpBGA	256	128	C
	LC4256B-75FN256AC <sup>1</sup>	256	2.5	7.5	Lead-Free fpBGA	256	128	C
	LC4256B-3FN256BC <sup>1</sup>	256	2.5	3	Lead-Free fpBGA	256	160	C
	LC4256B-5FN256BC <sup>1</sup>	256	2.5	5	Lead-Free fpBGA	256	160	C
	LC4256B-75FN256BC <sup>1</sup>	256	2.5	7.5	Lead-Free fpBGA	256	160	C
	LC4256B-3TN176C	256	2.5	3	Lead-Free TQFP	176	128	C
	LC4256B-5TN176C	256	2.5	5	Lead-Free TQFP	176	128	C
	LC4256B-75TN176C	256	2.5	7.5	Lead-Free TQFP	176	128	C
	LC4256B-3TN100C	256	2.5	3	Lead-Free TQFP	100	64	C
	LC4256B-5TN100C	256	2.5	5	Lead-Free TQFP	100	64	C
	LC4256B-75TN100C	256	2.5	7.5	Lead-Free TQFP	100	64	C

## ispMACH 4000V (3.3V) Lead-Free Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FTN256AI	256	3.3	5	Lead-free ftBGA	256	128	I
	LC4256V-75FTN256AI	256	3.3	7.5	Lead-free ftBGA	256	128	I
	LC4256V-10FTN256AI	256	3.3	10	Lead-free ftBGA	256	128	I
	LC4256V-5FTN256BI	256	3.3	5	Lead-free ftBGA	256	160	I
	LC4256V-75FTN256BI	256	3.3	7.5	Lead-free ftBGA	256	160	I
	LC4256V-10FTN256BI	256	3.3	10	Lead-free ftBGA	256	160	I
	LC4256V-5FN256AI <sup>1</sup>	256	3.3	5	Lead-free fpBGA	256	128	I
	LC4256V-75FN256AI <sup>1</sup>	256	3.3	7.5	Lead-free fpBGA	256	128	I
	LC4256V-10FN256AI <sup>1</sup>	256	3.3	10	Lead-free fpBGA	256	128	I
	LC4256V-5FN256BI <sup>1</sup>	256	3.3	5	Lead-free fpBGA	256	160	I
	LC4256V-75FN256BI <sup>1</sup>	256	3.3	7.5	Lead-free fpBGA	256	160	I
	LC4256V-10FN256BI <sup>1</sup>	256	3.3	10	Lead-free fpBGA	256	160	I
	LC4256V-5TN176I	256	3.3	5	Lead-free TQFP	176	128	I
	LC4256V-75TN176I	256	3.3	7.5	Lead-free TQFP	176	128	I
	LC4256V-10TN176I	256	3.3	10	Lead-free TQFP	176	128	I
	LC4256V-5TN144I	256	3.3	5	Lead-free TQFP	144	96	I
	LC4256V-75TN144I	256	3.3	7.5	Lead-free TQFP	144	96	I
	LC4256V-10TN144I	256	3.3	10	Lead-free TQFP	144	96	I
	LC4256V-5TN100I	256	3.3	5	Lead-free TQFP	100	64	I
	LC4256V-75TN100I	256	3.3	7.5	Lead-free TQFP	100	64	I
	LC4256V-10TN100I	256	3.3	10	Lead-free TQFP	100	64	I
LC4384V	LC4384V-5FTN256I	384	3.3	5	Lead-free ftBGA	256	192	I
	LC4384V-75FTN256I	384	3.3	7.5	Lead-free ftBGA	256	192	I
	LC4384V-10FTN256I	384	3.3	10	Lead-free ftBGA	256	192	I
	LC4384V-5FN256I <sup>1</sup>	384	3.3	5	Lead-free fpBGA	256	192	I
	LC4384V-75FN256I <sup>1</sup>	384	3.3	7.5	Lead-free fpBGA	256	192	I
	LC4384V-10FN256I <sup>1</sup>	384	3.3	10	Lead-free fpBGA	256	192	I
	LC4384V-5TN176I	384	3.3	5	Lead-free TQFP	176	128	I
	LC4384V-75TN176I	384	3.3	7.5	Lead-free TQFP	176	128	I
LC4512V	LC4512V-5FTN256I	512	3.3	5	Lead-free ftBGA	256	208	I
	LC4512V-75FTN256I	512	3.3	7.5	Lead-free ftBGA	256	208	I
	LC4512V-10FTN256I	512	3.3	10	Lead-free ftBGA	256	208	I
	LC4512V-5FN256I <sup>1</sup>	512	3.3	5	Lead-free fpBGA	256	208	I
	LC4512V-75FN256I <sup>1</sup>	512	3.3	7.5	Lead-free fpBGA	256	208	I
	LC4512V-10FN256I <sup>1</sup>	512	3.3	10	Lead-free fpBGA	256	208	I
	LC4512V-5TN176I	512	3.3	5	Lead-free TQFP	176	128	I
	LC4512V-75TN176I	512	3.3	7.5	Lead-free TQFP	176	128	I
	LC4512V-10TN176I	512	3.3	10	Lead-free TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.